What is claimed:

1. A thermally curable fluorinated o-aminophenol polymer or oligomer based on an o-aminophenol compound and an aromatic dicarboxylic acid compound, at least one of which is mono- or poly-fluorinated, and having thermosetting groups at both ends that undergo cross-linking reaction upon thermal treatment.

2. A thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1, wherein either one or both of the o-aminophenol compound and aromatic dicarboxylic acid compound contain at least one benzene ring substituted by one or more fluorine atoms or trifluoromethyl groups or at least one moiety with one or more trifluoromethyl groups.

3. A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1 or 2.

4. A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1 or 2.

5. A multilayer circuit board comprising a dielectric film according to claim 3.